

### Absolute Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-50	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-45	V
Emitter-Base Voltage	V <sub>EBO</sub>	-6.0	V
Continuous Collector Current	Ic	-100	mA
Peak Pulse Collector Current	I <sub>CM</sub>	-200	mA

#### Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Power Dissipation	(Note 5)	D	270	mW	
	(Note 6)	P <sub>D</sub>	925		
Thermal Resistance, Junction to Ambient	(Note 5)	$R_{ hetaJA}$	465	°C/W	
	(Note 6)		135		
Thermal Resistance, Junction to Lead	(Note 7)	$R_{ hetaJL}$	135	°C/W	
Operating and Storage and Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C	

## ESD Ratings (Note 8)

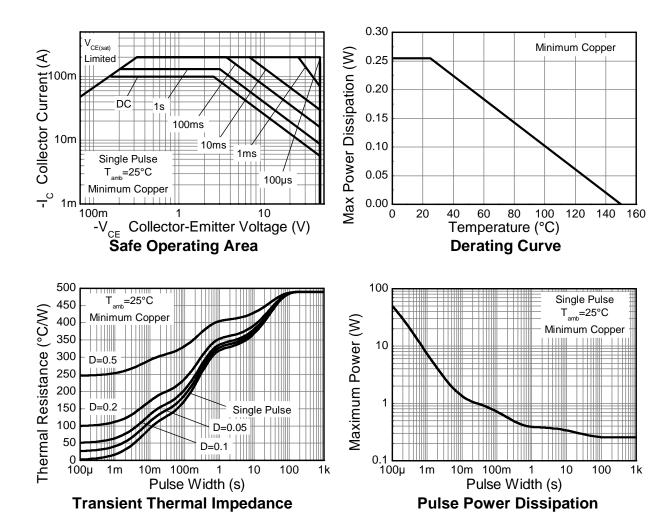
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	200	V	В

Notes:

- For the device mounted on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady state condition. The entire exposed collector pad is attached to the heatsink.
  Same as Note 5, except the exposed collector pad is mounted on 25mm x 25mm 2oz copper.
  Thermal resistance from junction to solder-point (on the exposed collector pad).
  Refer to JEDEC specification JESD22-A114 and JESD22-A115.



## **Thermal Characteristics and Derating Information**





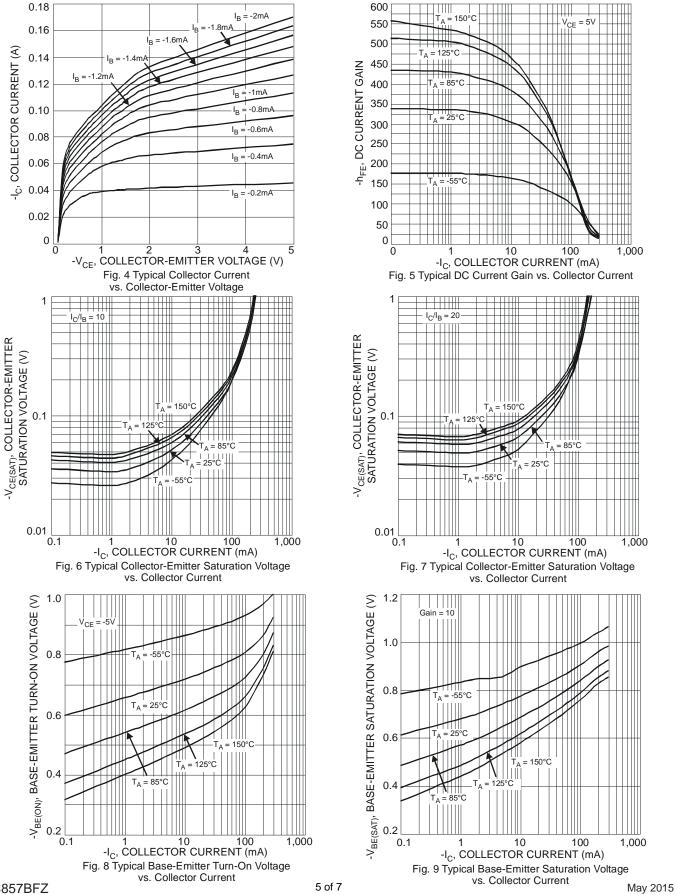
# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typical	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	-50	-100	_	V	$I_C = -50\mu A, I_B = 0$
Collector-Emitter Breakdown Voltage	BV <sub>CES</sub>	-50	-90	_	V	$I_C = -50\mu A, I_B = 0$
Collector-Emitter Breakdown Voltage (Note 9)	BV <sub>CEO</sub>	-45	-65	_	V	$I_{C} = -1 \text{mA}, I_{B} = 0$
Collector-Base Breakdown Voltage	BV <sub>EBO</sub>	-6.0	-8.5	_	V	$I_E = -50\mu A, I_C = 0$
Collector-Base Cutoff Current	I <sub>CBO</sub>	_	_	-15	nA	V <sub>CB</sub> = -40V
Collector-Emitter Cutoff Current	I <sub>CES</sub>	_	_	-15	nA	V <sub>CE</sub> = -40V
ON CHARACTERISTICS (Note 9)						
DC Current Gain	h <sub>FE</sub>	_ 200	340 330	— 470	-	$I_C = -10\mu A$ , $V_{CE} = -5.0V$ $I_C = -2.0mA$ , $V_{CE} = -5.0V$
Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>	_	-70 -300	-175 -500	mV	$I_C = -10$ mA, $I_B = -0.5$ mA $I_C = -100$ mA, $I_B = -5.0$ mA
Base-Emitter Saturation Voltage	V <sub>BE(sat)</sub>	_	-760 -885	-1,000 -1,100	mV	$I_C = -10$ mA, $I_B = -0.5$ mA $I_C = -100$ mA, $I_B = -5.0$ mA
Base-Emitter Voltage	V <sub>BE(on)</sub>	-600 —	-670 -715	-780 -850	mV	$I_C = -2.0$ mA, $V_{CE} = -5$ V $I_C = -10$ mA, $V_{CE} = -5$ V
SMALL SIGNAL CHARACTERISTICS						
Output Capacitance	C <sub>obo</sub>	_	2.0	_	pF	$V_{CB} = -10.0V$ , $f = 1.0MHz$ , $I_E = 0$
Current Gain-Bandwidth Product	f⊤	100	270	_	MHz	V <sub>CE</sub> = -5V, I <sub>C</sub> = -10mA, f = 100MHz

Note: 9. Measured under pulsed conditions. Pulse width  $\leq 300 \mu s$ . Duty cycle  $\leq 2\%$ .



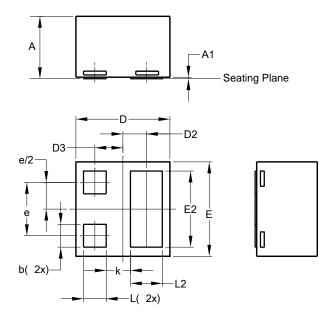
#### Typical Electrical Characteristics (@TA = +25°C, unless otherwise specified.)





# **Package Outline Dimensions**

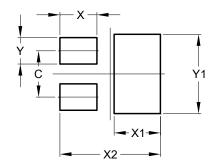
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



X2-DFN0606-3					
Dim	Min	Max	Тур		
Α	0.36	0.42	0.39		
A1	0	0.05	0.02		
b	0.10	0.20	0.15		
D	0.57	0.67	0.62		
D2	0.155 BSC				
D3	0.185 BSC				
Е	0.57	0.67	0.62		
E2	0.40	0.60	0.50		
е	0.35 BSC				
k	0.16 REF				
L	0.09	0.21	0.15		
L2	0.11	0.31	0.21		
All Dimensions in mm					

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.350
Х	0.280
X1	0.350
X2	0.760
Υ	0.200
V1	0.600

May 2015 © Diodes Incorporated



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